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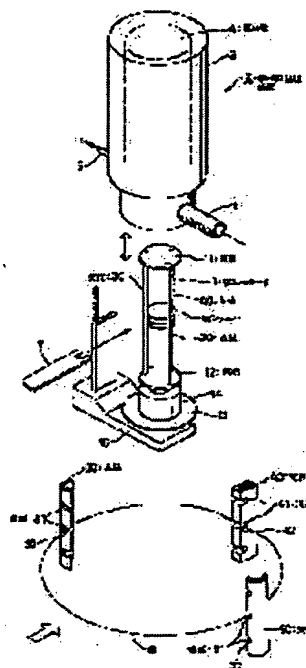
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(54) BOAT FOR HEAT TREATMENT

(57)Abstract:

PURPOSE: To reduce the generation of slip of matters to be treated by a method wherein when the matters to be treated are mounted on a boat, the edge parts of placement parts, which come into contact with these matters to be treated, are molded round.

CONSTITUTION: A wafer boat 1 has a circular ceiling plate 11 and a base plate 12, which are arranged in opposition to its upper and lower parts. Supports 20, 30 and 40 consisting of SiC, for example, are provided between these plates 11 and 12. Grooves 31 and 41 are respectively formed into the same pitch so as to support horizontally wafers W on their placement parts 32 and 42, have the same groove width, that is, the same upper and lower width, and moreover, the edge parts on at least the inner sides in the parts 32 and 42 are made an R and are subjected to molding work. As the very small R is made, a local stress in the wafers is reduced even if the wafers are brought into such a state that the end parts of the wafers W warp backward by the weights of the wafers W or the like and these wafers W are supported by the edge parts only. Therefore, the generation of slip of the wafers is suppressed.



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